

Abstract

Methods and devices for handling wafers during wafer processing are provided. One embodiment includes an apparatus for holding a wafer. The holding apparatus includes a pocket for receiving a wafer, and may include a mechanism allowing for the 5 wafer to be secured within the pocket. Methods are also included for preparing a wafer for fabrication processes by the use of a wafer holding apparatus. These methods may include applying a layer of photoresist to the surface of a wafer.